

Gigabit 4x4 CROSSPOINT SWITCH

FEATURES

- Up to 4.25 Gbps Operation
- Non-blocking Architecture Allows Each Output to be Connected to Any Input
- 30 ps of Deterministic Jitter
- Selectable Transmit Pre-Emphasis Per Lane
- Selectable Receive Equalization
- Available Packaging 48 Pin QFN
- Propagation Delay Times: 500 ps Typical
- Inputs Electrically Compatible With CML Signal Levels
- Operates From a Single 3.3-V Supply
- Ability to 3-STATE outputs
- Low Power: 560 mW
- Integrated Termination Resistors

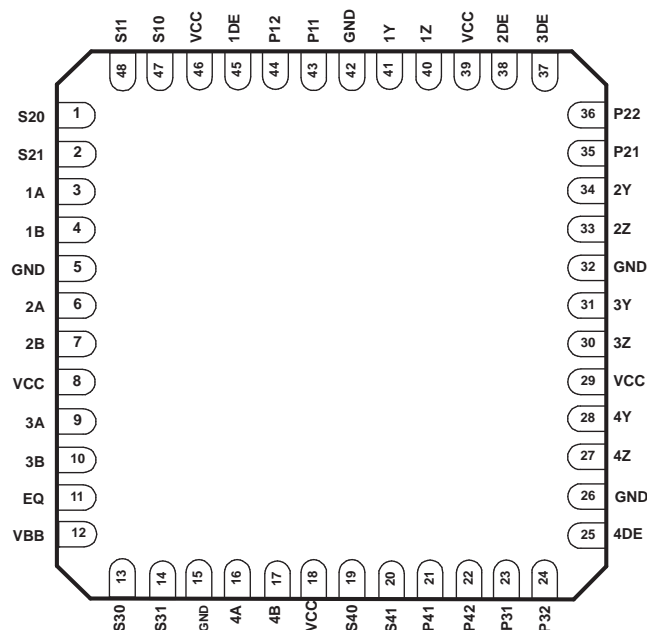
APPLICATIONS

- Clock Buffering/Clock MUXing
- Wireless Base Stations
- High-Speed Network Routing
- Telecom/Datacom
- XAUI 802.3ae Protocol Backplane Redundancy

DESCRIPTION

The SN65LVCP404 is a 4x4 non-blocking crosspoint switch in a flow-through pin-out allowing for ease in PCB layout. VML signaling is used to achieve a high-speed data throughput while using low power. Each of the output drivers includes a 4:1 multiplexer to allow any input to be routed to any output. Internal signal paths are fully differential to achieve the high signaling speeds while maintaining low signal skews. The SN65LVCP404 incorporates 100-Ω termination resistors for those applications where board space is a premium. Built-in transmit pre-emphasis and receive equalization for superior signal integrity performance.

The SN65LVCP404 is characterized for operation from -40°C to 85°C.

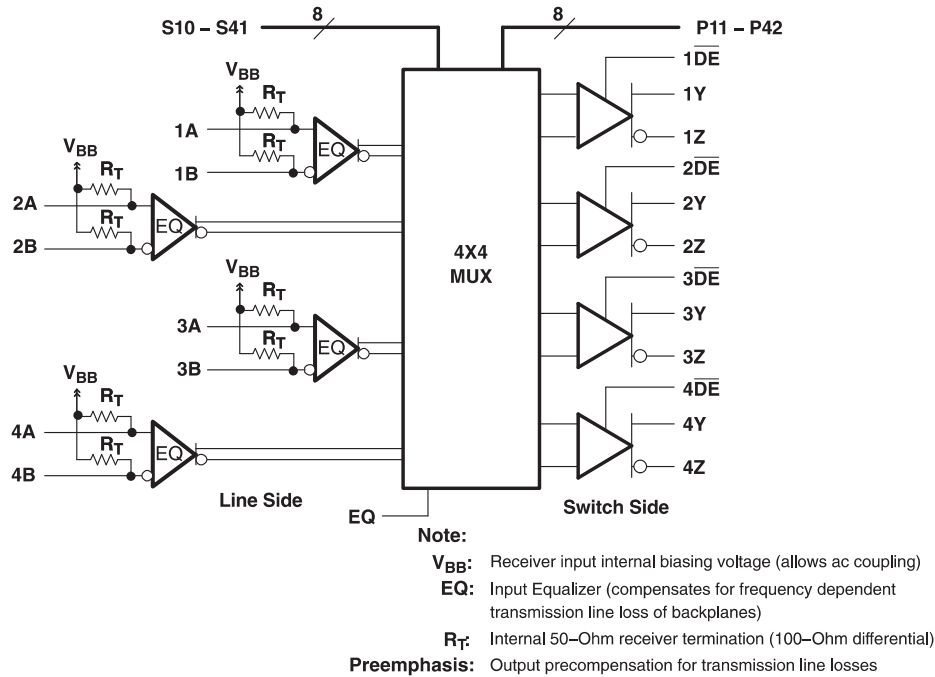


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

LOGIC DIAGRAM



TERMINAL FUNCTIONS

TERMINAL		TYPE	DESCRIPTION
NAME	NO.		
High Speed I/O			
xA xB	3, 6, 9, 16 4, 7, 10, 17	Differential Inputs (with 50-Ω termination to Vbb) xA=P; xB=N	Line Side Differential Inputs CML compatible
xY xZ	41, 34, 31, 28 40, 33, 30, 27	Differential Output xY=P; xZ=N	Switch Side Differential Outputs. VML
Control Signals			
xDE	45, 38, 37, 25	Input	Data Enable; Active Low; LVTTTL; When not enabled the ouput is in 3-STATE mode for power savings
S10 - S41	1, 2, 13, 14, 19, 20, 47, 48	Input; S1x = Channel 1 bit one	Switching Selection; LVTTTL
P11-P42	43, 44, 35, 36, 23, 24, 21, 22	Input; P1x- Channel 1 bit one	Output Preemphasis Control; LVTTTL
EQ	11	Input; Selection for receive equalization setting	EQ = 1 (default) is for the 5 dB setting, EQ = 0 is for the 12 dB setting
Power Supply			
VCC	8, 18, 29, 39, 46	Power	Power Supply 3.3v ±5%
GND	5, 15, 26, 32, 42		
Thermal Pad			The ground center pad of the package must be connected to GND plane.
VBB	12	Input	Receiver input biasing voltage. For ac coupling, VBB should be left floating for optimal bias value. For dc coupling, VBB can driven to change the common mode. VBB should not be tied to ground.

EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS

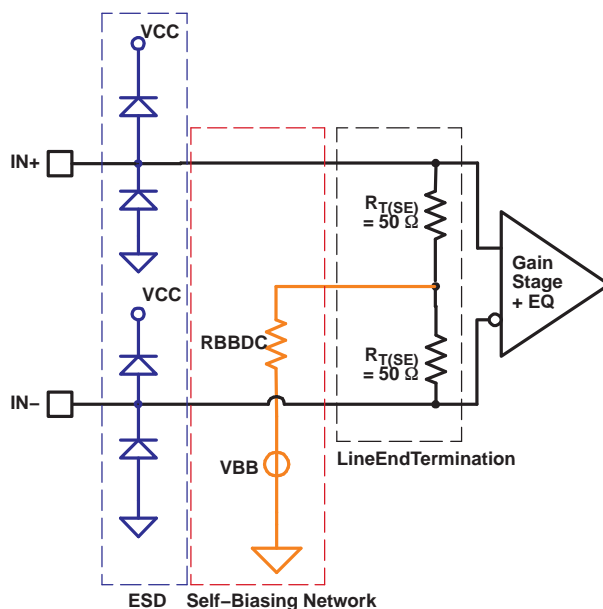


Figure 1. Equivalent Input Circuit Design

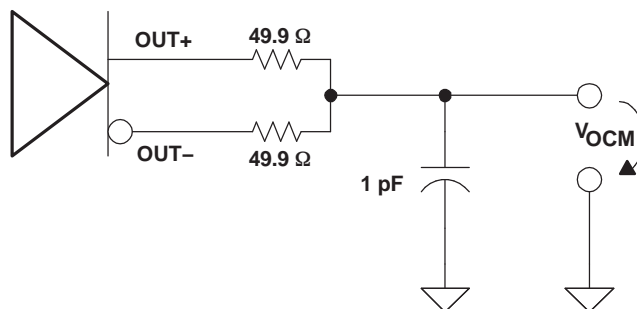


Figure 2. Common-Mode Output Voltage Test Circuit

Table 1. CROSSPOINT LOGIC TABLES

OUTPUT CHANNEL 1			OUTPUT CHANNEL 2			OUTPUT CHANNEL 3			OUTPUT CHANNEL 4		
CONTROL PINS		INPUT SELECTED	CONTROL PINS		INPUT SELECTED	CONTROL PINS		INPUT SELECTED	CONTROL PINS		INPUT SELECTED
S10	S11	1Y/1Z	S20	S21	2Y/2Z	S30	S31	3Y/3Z	S40	S41	4Y/4Z
0	0	1A/1B	0	0	1A/1B	0	0	1A/1B	0	0	1A/1B
0	1	2A/2B	0	1	2A/2B	0	1	2A/2B	0	1	2A/2B
1	0	3A/3B	1	0	3A/3B	1	0	3A/3B	1	0	3A/3B
1	1	4A/4B	1	1	4A/4B	1	1	4A/4B	1	1	4A/4B

AVAILABLE OPTIONS

T _A	DESCRIPTION	PACKAGED DEVICE ⁽¹⁾
		RGZ (48 pin)
-40°C to 85°C	Serial multiplexer	SN65LVCP404

(1) The package is available taped and reeled. Add an R suffix to device types (e.g., SN65LVCP404RGZR).

PACKAGE THERMAL CHARACTERISTICS

PACKAGE THERMAL CHARACTERISTICS ⁽¹⁾		NOM	UNIT
θ_{JA} (junction-to-ambient)	4-layer JEDEC Board (JESD51-7) using eight GND-vias $\theta=0.2$ on the center pad as shown in the section: <i>Recommended PCB footprint</i> with boundary and environment conditions of JEDEC Board (JESD51-2)	33	°C/W
θ_{JB} (junction-to-board)		20	°C/W
θ_{JC} (junction-to-case)		23.6	°C/W
PSI-jt (junction-to-top pseudo)		0.6	°C/W
PSI-jb (junction-to-board pseudo)		19.4	°C/W
θ_{JP} (junction-to-pad)		5.4	°C/W

(1) See application note [SPRA953](http://www-s.ti.com/sc/psheets/spra953/spra953.pdf) for a detailed explanation of thermal parameters (<http://www-s.ti.com/sc/psheets/spra953/spra953.pdf>).

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			UNIT
V _{CC}	Supply voltage range ⁽²⁾		–0.5 V to 6 V
Voltage range	Control inputs, all outputs		–0.5 V to (V _{CC} + 0.5 V)
	Receiver inputs		–0.5 V to 4 V
ESD	Human Body Model ⁽³⁾	All pins	3 kV
	Charged-Device Model ⁽⁴⁾	All pins	500 V
T _J	Maximum junction temperature		See Package Thermal Characteristics Table
Moisture sensitivity level			2
Reflow temperature package soldering, 4 seconds			260°C

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.

(3) Tested in accordance with JEDEC Standard 22, Test Method A114-A.

(4) Tested in accordance with JEDEC Standard 22, Test Method C101.

RECOMMENDED OPERATING CONDITIONS

			MIN	NOM	MAX	UNIT
dR	Operating data rate				4.25	Gbps
V _{CC}	Supply voltage		3.135	3.3	3.465	V
V _{CC(N)}	Supply voltage noise amplitude	10 Hz to 2.125 GHz			20	mV
T _J	Junction temperature				125	°C
T _A	Operating free-air temperature ⁽¹⁾		-40		85	°C
DIFFERENTIAL INPUTS						
V _{ID}	Receiver peak-to-peak differential input voltage ⁽²⁾	dR _(in) ≤ 4.25 Gbps	100		1750	mV _{PP}
		1.25 Gbps < dR _(in) ≤ 4.25 Gbps	100		1560	mV _{PP}
		dR _(in) > 4.25 Gbps	100		1000	mV _{PP}
V _{ICM}	Receiver common-mode input voltage	Note: for best jitter performance ac coupling is recommended.	1.5	1.6	V _{CC} - $\frac{ V_{ID} }{2}$	V
CONTROL INPUTS						
V _{IH}	High-level input voltage		2		V _{CC} + 0.3	V
V _{IL}	Low-level input voltage		-0.3		0.8	V
DIFFERENTIAL OUTPUTS						
R _L	Differential load resistance		80	100	120	Ω

(1) Maximum free-air temperature operation is allowed as long as the device maximum junction temperature is not exceeded.

(2) Differential input voltage V_{ID} is defined as |IN+ – IN–|.

ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
DIFFERENTIAL INPUTS						
V _{IT+}	Positive going differential input high threshold				50	mV
V _{IT−}	Negative going differential input low threshold		−50			mV
A _(EQ)	Equalizer gain	at 1.875 GHz (EQ=0)		12		dB
R _{T(D)}	Termination resistance, differential		80	100	120	Ω
V _{BB}	Open-circuit Input voltage (input self-bias voltage)	AC-coupled inputs		1.6		V
R _(BBDC)	Biasing network dc impedance			30		kΩ
R _(BBAC)	Biasing network ac impedance	375 MHz		42		Ω
		2.125 GHz		8.4		
DIFFERENTIAL OUTPUTS						
V _{ODH}	High-level output voltage	R _L = 100 Ω ±1%, Px_2 = Px_1=0; 4 Gbps alternating 1010-pattern; Figure 3		650		mV _{PP}
V _{ODL}	Low-level output voltage			−650		mV _{PP}
V _{ODB(PP)}	Output differential voltage without preemphasis ⁽²⁾			1000	1300	1500
V _{OCM}	Output common mode voltage	See Figure 2		1.65		V
ΔV _{OC(SS)}	Change in steady-state common-mode output voltage between logic states				1	

(1) All typical values are at T_A = 25°C and V_{CC} = 3.3 V supply unless otherwise noted. They are for reference purposes and are not production tested.

(2) Differential output voltage V_(ODB) is defined as |OUT+ – OUT–|.

ELECTRICAL CHARACTERISTICS (continued)

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
V _(PE) Output preemphasis voltage ratio, $\frac{V_{\text{ODB(PP)}}}{V_{\text{ODPE(PP)}}}$	R _L = 100 Ω ±1%; x = L or S; See Figure 3	Px_2:Px_1 = 00		0	dB
		Px_2:Px_1 = 01		3	
		Px_2:Px_1 = 10		6	
		Px_2:Px_1 = 11		9	
t _(PRE) Preemphasis duration measurement	Output preemphasis is set to 9 dB during test Px_x = 1; Measured with a 100-MHz clock signal; R _L = 100 Ω ±1%, See Figure 4		175		ps
r _o Output resistance	Differential on-chip termination between OUT+ and OUT–		100		Ω
CONTROL INPUTS					
I _{IH} High-level Input current	VIN = VCC			5	μA
I _{IL} Low-level Input current	VIN = GND	-125	-90		μA
R _(PU) Pullup resistance			35		kΩ
POWER CONSUMPTION					
P _D Device power dissipation	All outputs terminated 100 Ω		560	750	mW
P _Z Device power dissipation in 3-State	All outputs in 3-state			600	mW
I _{CC} Device current consumption	All outputs terminated 100 Ω PRBS 2 ⁷⁻¹ pattern at 4.25 Gbps			220	mA

SWITCHING CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
MULTIPLEXER					
t _(SM) Multiplexer switch time	Multiplexer to valid output		3	6	ns
DIFFERENTIAL OUTPUTS					
t _{PLH} Low-to-high propagation delay	Propagation delay input to output See Figure 6		0.5	0.7	ns
t _{PHL} High-to-low propagation delay			0.5	0.7	ns
t _r Rise time	20% to 80% of V _{O(DB)} ; Test Pattern: 100-MHz clock signal; See Figure 5 and Figure 8		80		ps
t _f Fall time			80		ps
t _{sk(p)} Pulse skew, t _{PHL} – t _{PLH} ⁽²⁾				20	ps
t _{sk(o)} Output skew ⁽³⁾	All outputs terminated with 100 Ω		25	100	ps
t _{sk(pp)} Part-to-part skew ⁽⁴⁾				300	ps
t _{zd} 3-State switch time to Disable	Assumes 50 Ω to V _{cm} and 150 pF load on each output			20	ns
t _{ze} 3-State switch time to Enable	Assumes 50 Ω to V _{cm} and 150 pF load on each output			10	ns
RJ Device random jitter, rms	See Figure 8 for test circuit. BERT setting 10 ⁻¹⁵ Alternating 10-pattern.		0.8	2	ps-rms

(1) All typical values are at 25°C and with 3.3 V supply unless otherwise noted.

(2) t_{sk(p)} is the magnitude of the time difference between the t_{PLH} and t_{PHL} of any output of a single device.(3) t_{sk(o)} is the magnitude of the time difference between the t_{PLH} and t_{PHL} of any two outputs of a single device.(4) t_{sk(pp)} is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

SWITCHING CHARACTERISTICS (continued)

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP ⁽¹⁾	MAX	UNIT
DJ	Intrinsic deterministic device jitter ⁽⁵⁾⁽⁶⁾ , peak-to-peak	0 dB preemphasis (PRE _x = 0); See Figure 8 for the test circuit.	PRBS 2 ⁷⁻¹ pattern	4.25 Gbps			30	ps
	Absolute deterministic output jitter ⁽⁷⁾ , peak-to-peak	0 dB preemphasis (PRE _x = 0); See Figure 8 for the test circuit.	PRBS 2 ⁷⁻¹ pattern	1.25Gbps; EQ=1 Over 25-inch FR4 trace 4.25 Gbps; EQ=0 Over FR4 trace 2-inch to 43 inches long		7	20	ps

- (5) Intrinsic deterministic device jitter is a measurement of the deterministic jitter contribution from the device. It is derived by the equation $(DJ_{(OUT)} - DJ_{(IN)})$, where $DJ_{(OUT)}$ is the total peak-to-peak deterministic jitter measured at the output of the device in PSPP. $DJ_{(IN)}$ is the peak-to-peak deterministic jitter of the pattern generator driving the device.
- (6) The SN65LVCP404 built-in passive input equalizer compensates for ISI. For a 25-inch FR4 transmission line with 8-mil trace width, the LVCP404 typically reduces jitter by 60 ps from the device input to the device output.
- (7) Absolute deterministic output jitter reflects the deterministic jitter measured at the SN65LVCP404 output. The value is a real measured value with a Bit error tester as described in Figure 8. The absolute DJ reflects the sum of all deterministic jitter components accumulated over the link: $DJ_{(absolute)} = DJ_{(Signal\ generator)} + DJ_{(transmission\ line)} + DJ_{(intrinsic(LVCP404))}$.

Table 2. Preemphasis Controls PL_2, PL_1, PS_2, and PS_1

Px_2 ⁽¹⁾	Px_1 ⁽¹⁾	OUTPUT PREEMPHASIS LEVEL IN dB	OUTPUT LEVEL IN mVpp		TYPICAL FR4 TRACE LENGTH
			DE-EMPHASIZED	PRE-EMPHASIZED	
0	0	0 dB	1200	1200	10 inches of FR4 trace
0	1	3 dB	850	1200	20 inches of FR4 trace
1	0	6 dB	600	1200	30 inches of FR4 trace
1	1	9 dB	425	1200	40 inches of FR4 trace

(1) x = L or S

Table 3. Receive Equalization Settings

EQ	EQUALIZATION	TYPICAL TRACE
1	5 dB	25 inches of FR4
0	12 dB	43 inches of FR4

PARAMETER MEASUREMENT INFORMATION

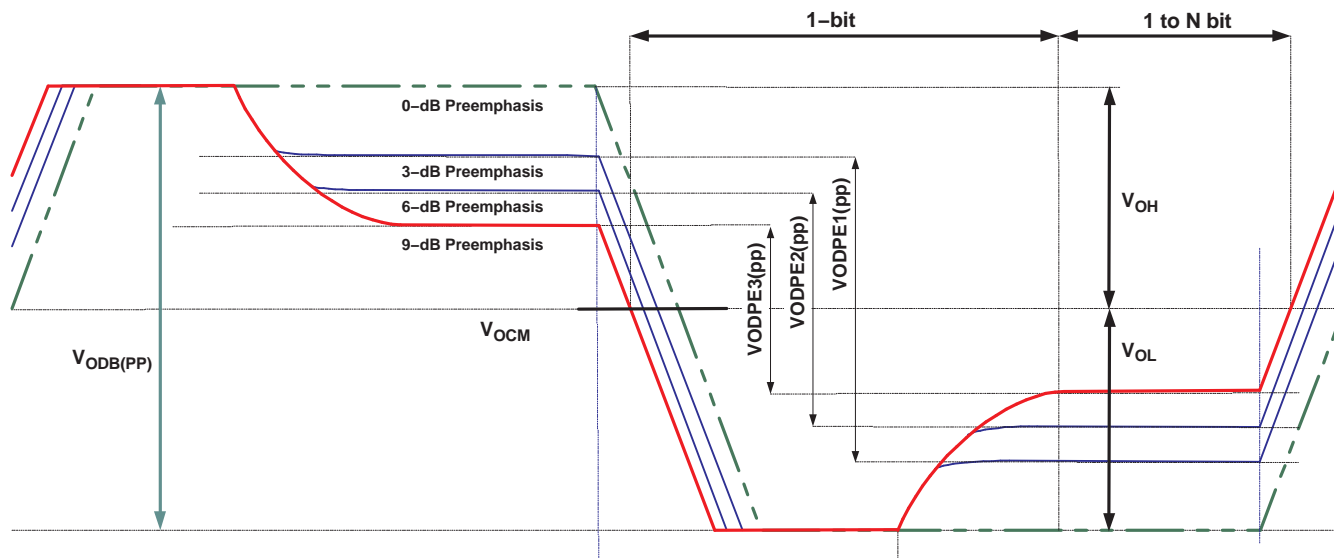


Figure 3. Preemphasis and Output Voltage Waveforms and Definitions

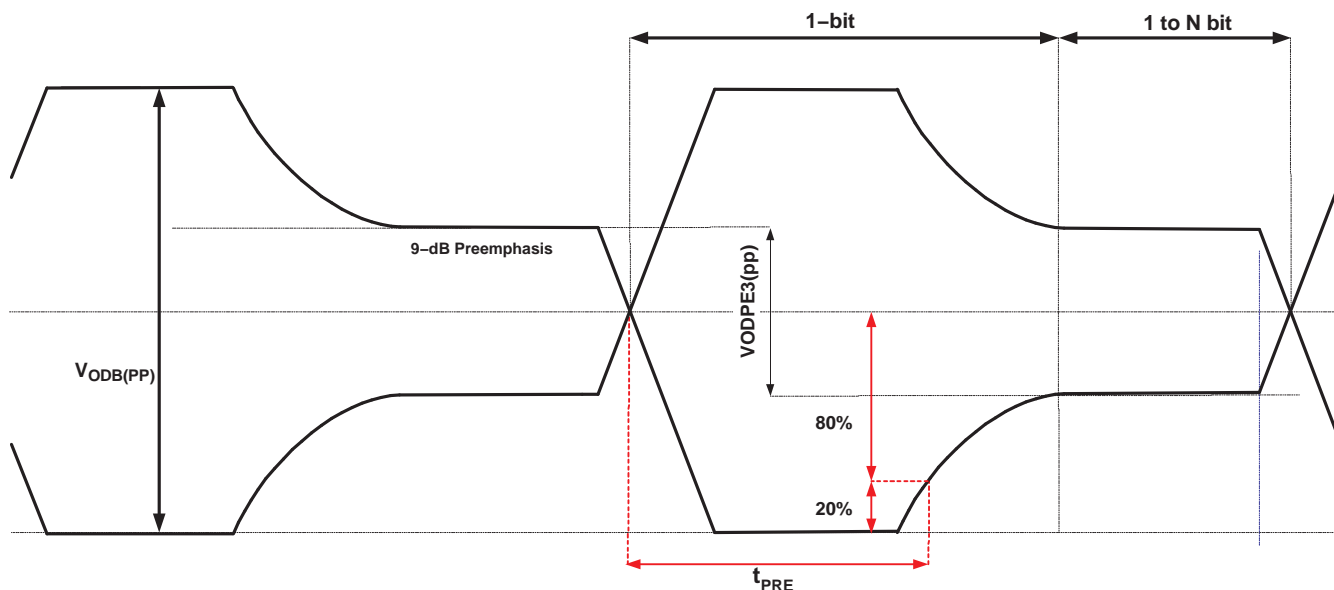


Figure 4. t_{PRE} Preemphasis Duration Measurement

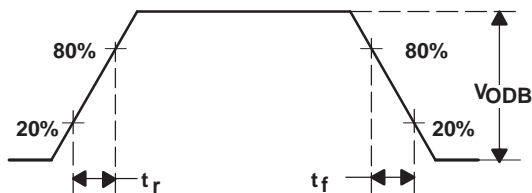


Figure 5. Driver Output Transition Time

PARAMETER MEASUREMENT INFORMATION (continued)

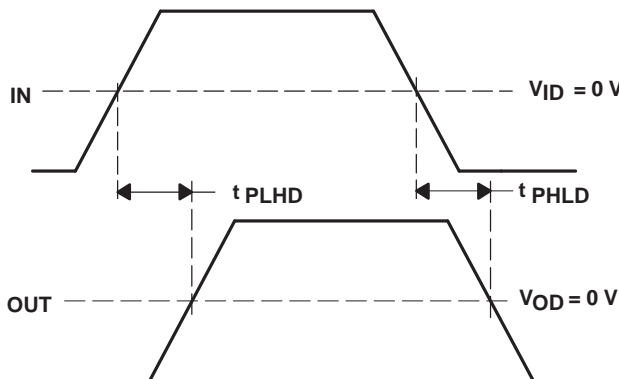
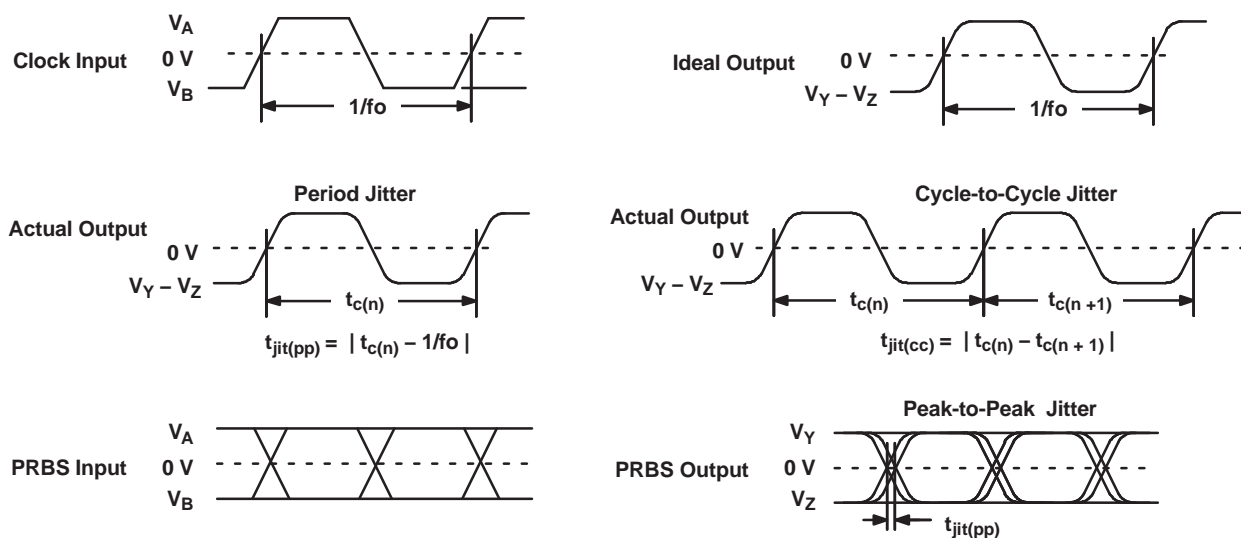


Figure 6. Propagation Delay Input to Output



- A. All input pulses are supplied by an Agilent 81250 Stimulus System.
- B. The measurement is made with the AgilentParBert measurement software.

Figure 7. Driver Jitter Measurement Waveforms

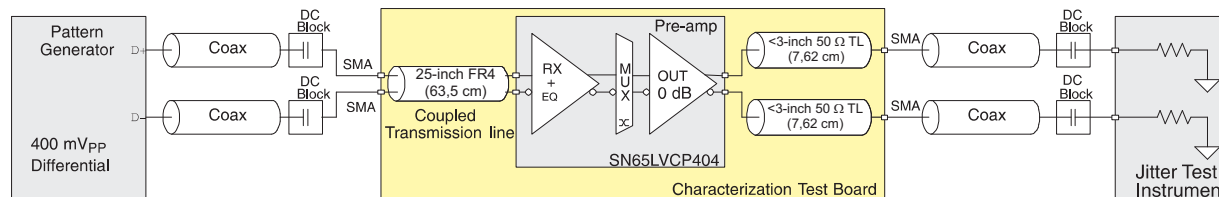
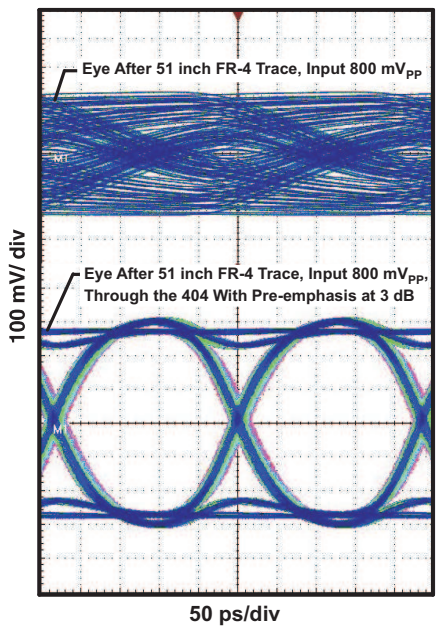


Figure 8. AC Test Circuit — Jitter and Output Rise Time Test Circuit

The SN65LVCP404 input equalizer provides 5-dB frequency gain to compensate for frequency loss of a shorter backplane transmission line. For characterization purposes, a 25-inch (63.5 cm) FR-4 coupled transmission line is used in place of the backplane trace. The 25-inch trace provides roughly 5 dB of attenuation between 375 MHz and 2.125 GHz, representing closely the characteristics of a short backplane trace. The loss tangent of the FR4 in the test board is 0.018 with an effective $\epsilon(r)$ of 4.1.

TYPICAL DEVICE BEHAVIOR



NOTE: 51 Inches (129.54 cm) Input Trace, dR = 4.25 Gbps; 2^{7-1} PRBS
Figure 9. Data Input and Output Pattern

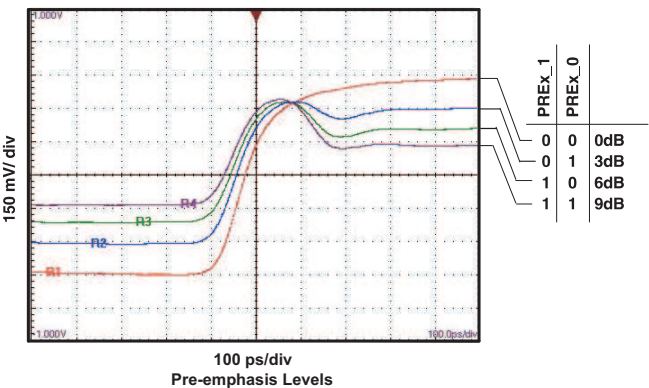


Figure 10. Preemphasis Signal Shape

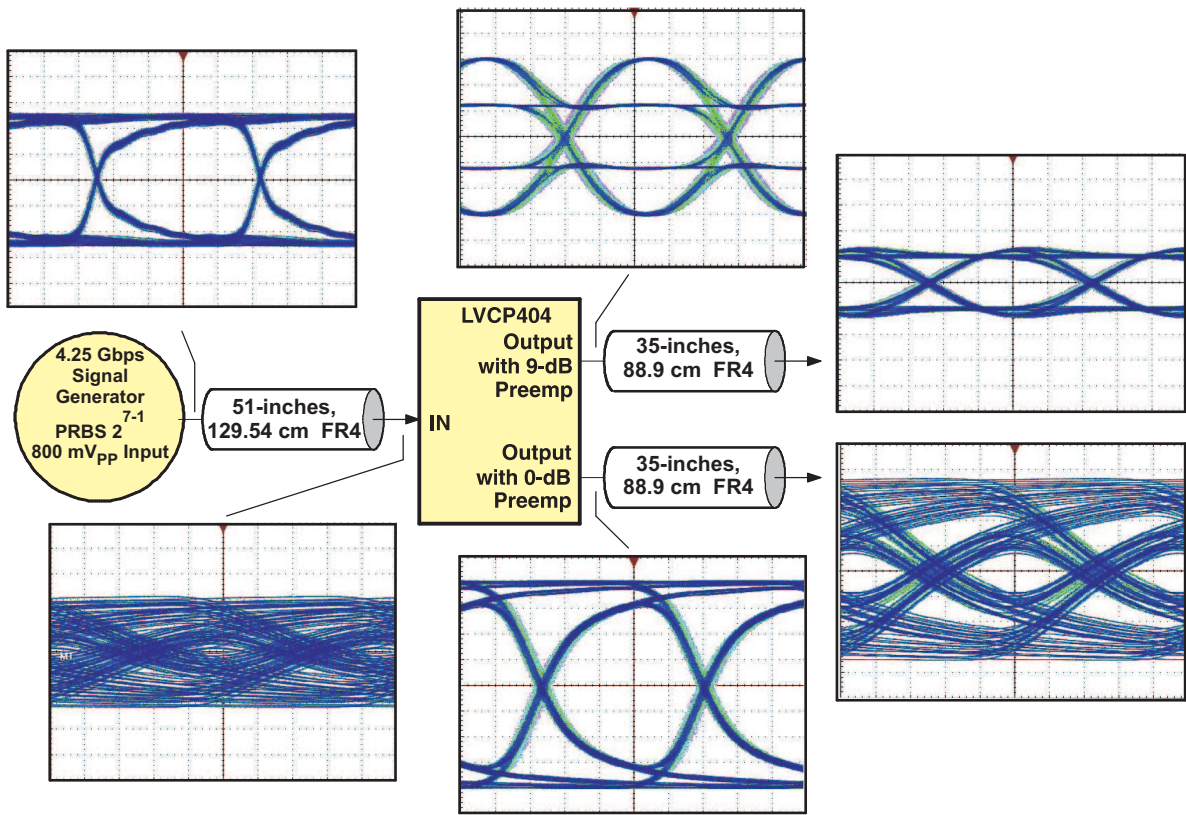


Figure 11. Data Output Pattern

TYPICAL CHARACTERISTICS

**DETERMINISTIC OUTPUT JITTER
vs
DATA RATE**

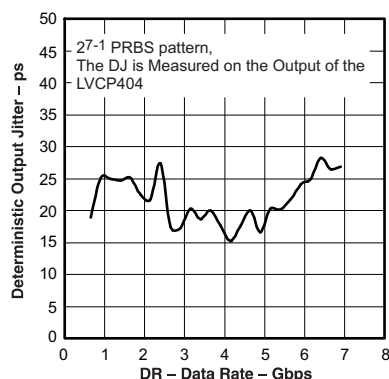


Figure 12.

**DETERMINISTIC OUTPUT JITTER
vs
DIFFERENTIAL INPUT AMPLITUDE**

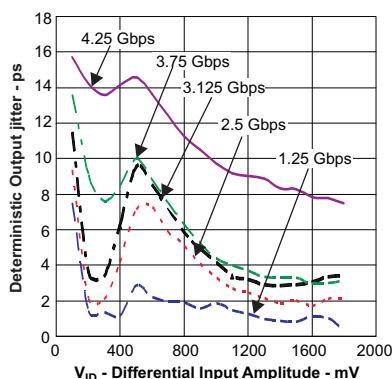


Figure 13.

**DIFFERENTIAL OUTPUT VOLTAGE
vs
DATA RATE**

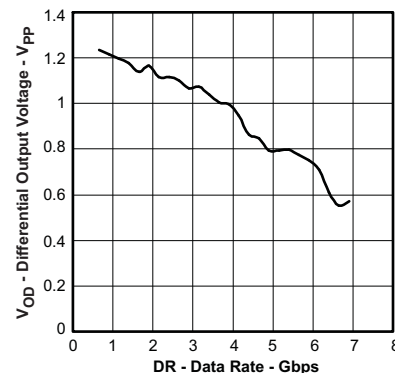


Figure 14.

**SUPPLY NOISE vs DETERMINISTIC
JITTER
vs
DATA RATE**

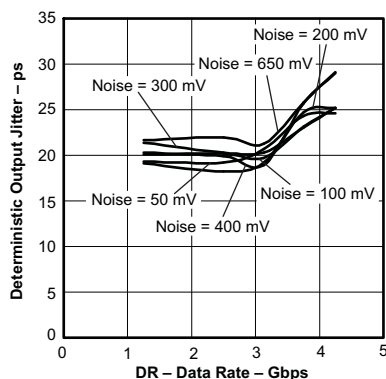


Figure 15.

**DETERMINISTIC OUTPUT JITTER
vs
COMMON-MODE INPUT VOLTAGE**

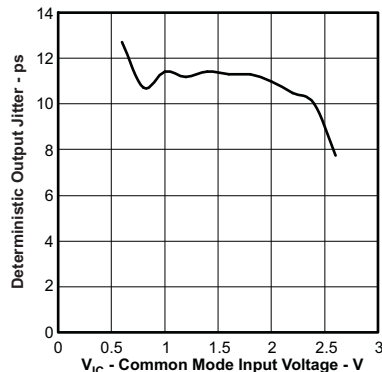
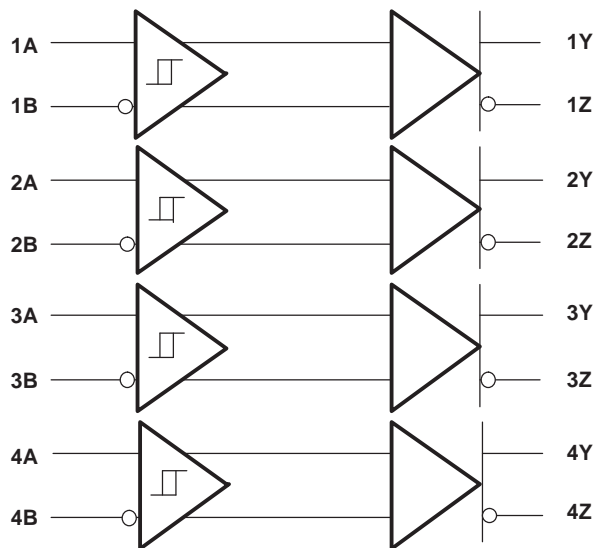


Figure 16.

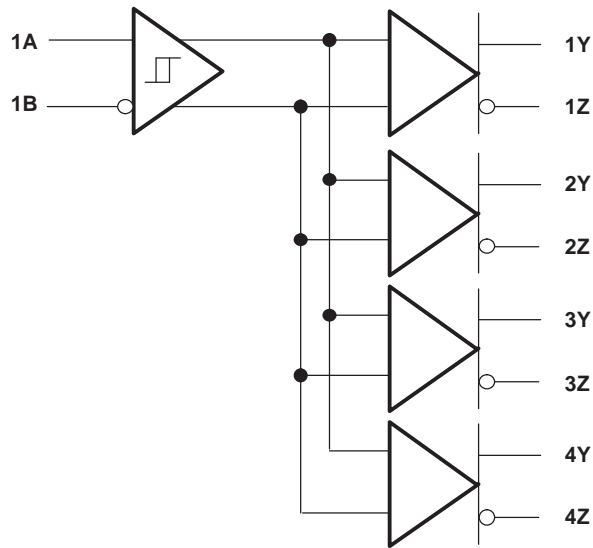
APPLICATION INFORMATION

CONFIGURATION EXAMPLES

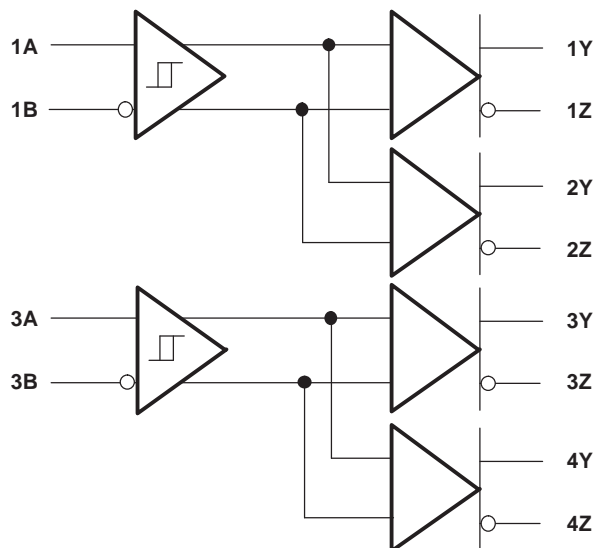
S10	S11	S20	S21
0	0	0	1
S30	S31	S40	S41
1	0	1	1



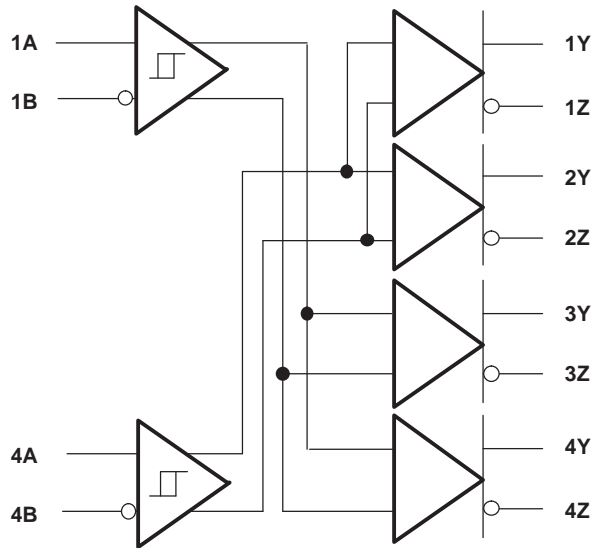
S10	S11	S20	S21
0	0	0	0
S30	S31	S40	S41
0	0	0	0



S10	S11	S20	S21
0	0	0	0
S30	S31	S40	S41
1	0	1	0



S10	S11	S20	S21
1	1	1	1
S30	S31	S40	S41
0	0	0	0



BANDWIDTH REQUIREMENTS

Error free transmission of data over a transmission line has specific bandwidth demands. It is helpful to analyze the frequency spectrum of the transmit data first. For an 8B10B coded data stream at 3.75 Gbps of random data, the highest bit transition density occurs with a 1010 pattern (1.875 GHz). The least transition density in 8B10B allows for five consecutive ones or zeros. Hence, the lowest frequency of interest is $1.875 \text{ GHz}/5 = 375 \text{ MHz}$. Real data signals consist of higher frequency components than sine waves due to the fast rise time. The faster the rise time, the more bandwidth becomes required. For 80-ps rise time, the highest important frequency component is at least $0.6/(\pi \times 80 \text{ ps}) = 2.4 \text{ GHz}$. Figure 17 shows the Fourier transformation of the 375-MHz and 1.875-GHz trapezoidal signal.

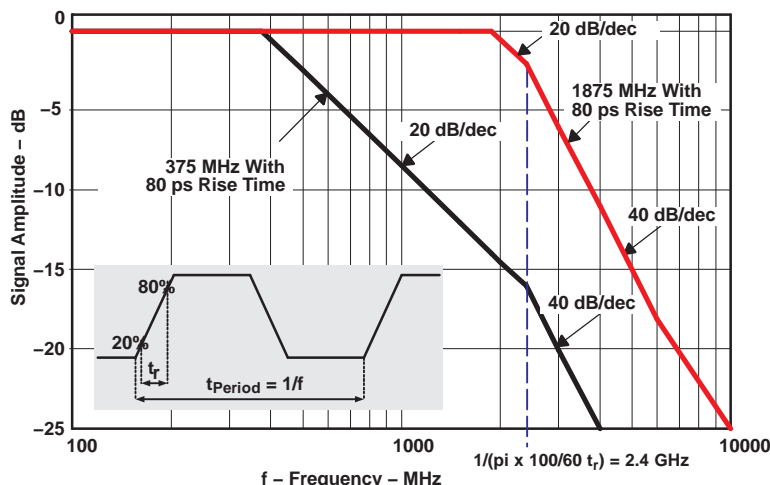


Figure 17. Approximate Frequency Spectrum of the Transmit Output Signal With 80 ps Rise Time

The spectrum analysis of the data signal suggests building a backplane with little frequency attenuation up to 2 GHz. Practically, this is achievable only with expensive, specialized PCB material. To support material like FR4, a compensation technique is necessary to compensate for backplane imperfections.

EXPLANATION OF EQUALIZATION

Backplane designs differ widely in size, layer stack-up, and connector placement. In addition, the performance is impacted by trace architecture (trace width, coupling method) and isolation from adjacent signals. Common to most commercial backplanes is the use of FR4 as board material and its related high-frequency signal attenuation. Within a backplane, the shortest to longest trace lengths differ substantially – often ranging from 8 inches up to 40 inches. Increased loss is associated with longer signal traces. In addition, the backplane connector often contributes a good amount of signal attenuation. As a result, the frequency signal attenuation for a 300-MHz signal might range from 1 dB to 4 dB while the corresponding attenuation for a 2-GHz signal might span 6 dB to 24 dB. This frequency dependent loss causes distortion jitter on the transmitted signal. Each LVCP404 receiver input incorporates an equalizer and compensates for such frequency loss. The SN65LVCP404 equalizer provides 5 dB of frequency gain between 375 MHz and 1.875 GHz, compensating roughly for 20 inches of FR4 material with 8-mil trace width. Distortion jitter improvement is substantial, often providing more than 30-ps jitter reduction. The 5-dB compensation is sufficient for most short backplane traces. For longer trace lengths, it is recommended to enable transmit preemphasis in addition.

SETTING THE PREEMPHASIS LEVEL

The receive equalization compensates for ISI. This reduces jitter and opens the data eye. In order to find the best preemphasis setting for each link, calibration of every link is recommended. Assuming each link consists of a transmitter (with adjustable pre-emphasis such as LVCP404) and the LVCP404 receiver, the following steps are necessary:

1. Set the transmitter and receiver to 0-dB preemphasis; record the data eye on the LVCP404 receiver output.
2. Increase the transmitter preemphasis until the data eye on the LVCP404 receiver output looks the cleanest.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN65LVCP404RGZR	Active	Production	VQFN (RGZ) 48	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	LVCP404
SN65LVCP404RGZR.B	Active	Production	VQFN (RGZ) 48	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	LVCP404
SN65LVCP404RGZT	Active	Production	VQFN (RGZ) 48	250 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	LVCP404
SN65LVCP404RGZT.B	Active	Production	VQFN (RGZ) 48	250 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	LVCP404
SN65LVCP404RGZTG4	Active	Production	VQFN (RGZ) 48	250 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	LVCP404
SN65LVCP404RGZTG4.B	Active	Production	VQFN (RGZ) 48	250 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	LVCP404

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LVCP404RGZR	VQFN	RGZ	48	2500	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2
SN65LVCP404RGZT	VQFN	RGZ	48	250	180.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2
SN65LVCP404RGZTG4	VQFN	RGZ	48	250	180.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LVCP404RGZR	VQFN	RGZ	48	2500	353.0	353.0	32.0
SN65LVCP404RGZT	VQFN	RGZ	48	250	213.0	191.0	35.0
SN65LVCP404RGZTG4	VQFN	RGZ	48	250	213.0	191.0	35.0

GENERIC PACKAGE VIEW

RGZ 48

VQFN - 1 mm max height

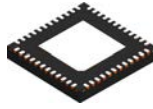
7 x 7, 0.5 mm pitch

PLASTIC QUADFLAT PACK- NO LEAD

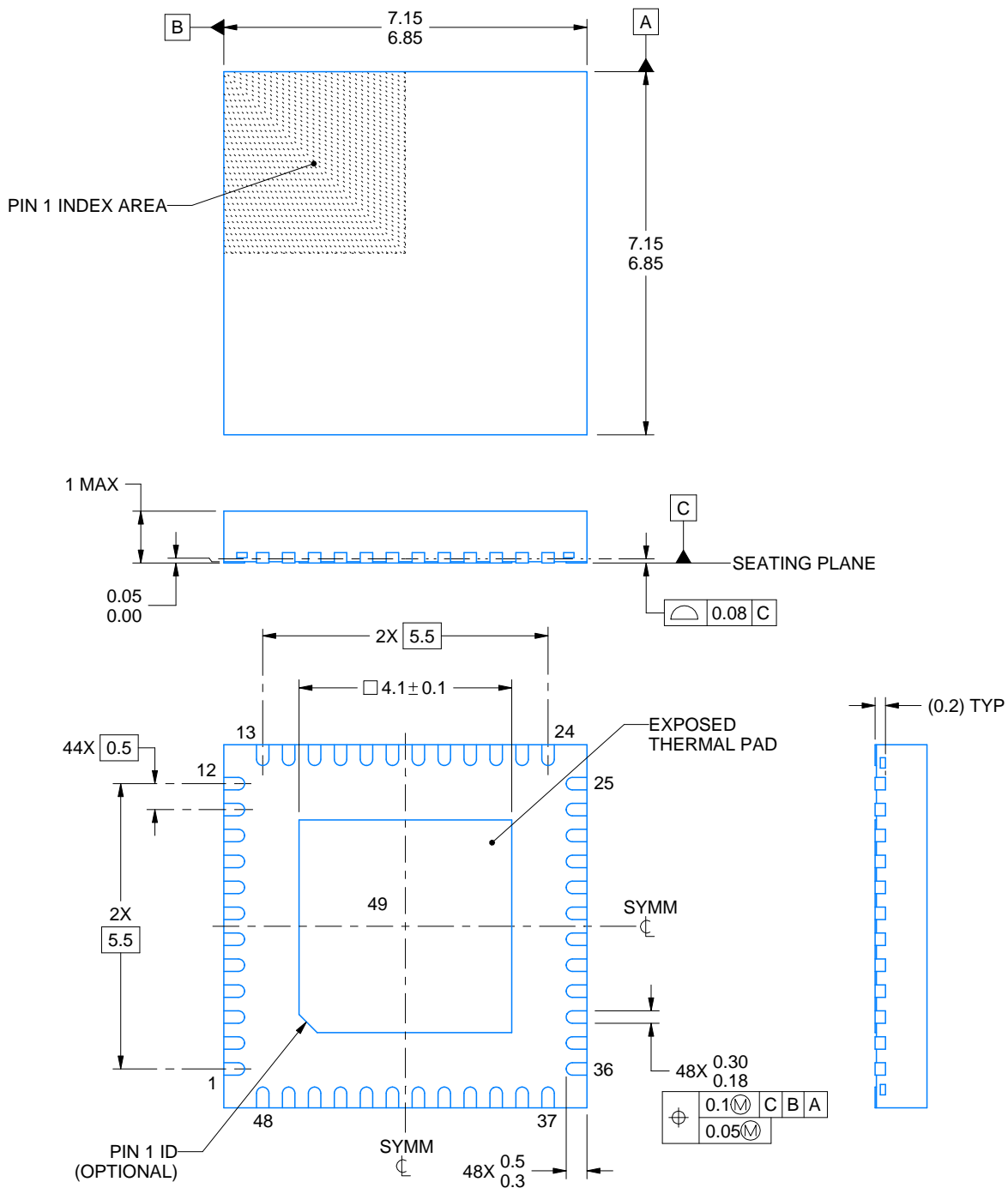


Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4224671/A

RGZ0048B**PACKAGE OUTLINE****VQFN - 1 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



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NOTES:

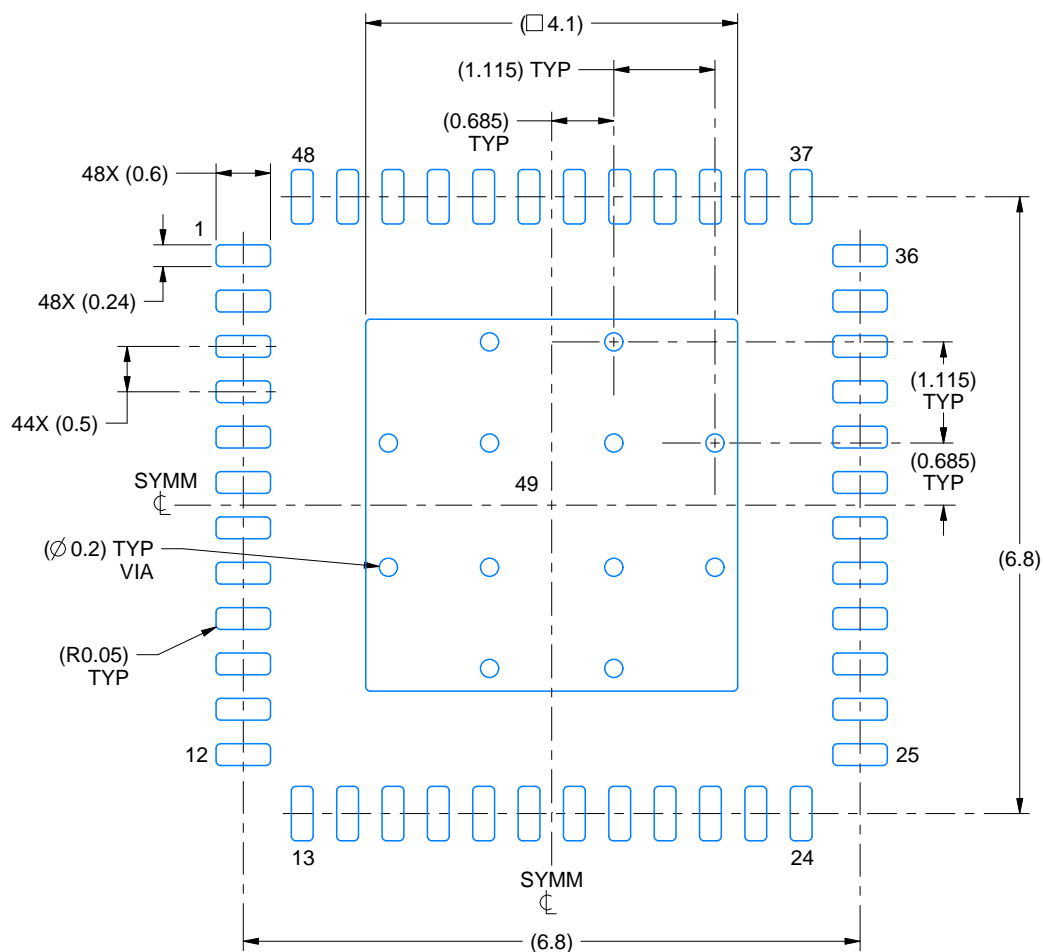
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

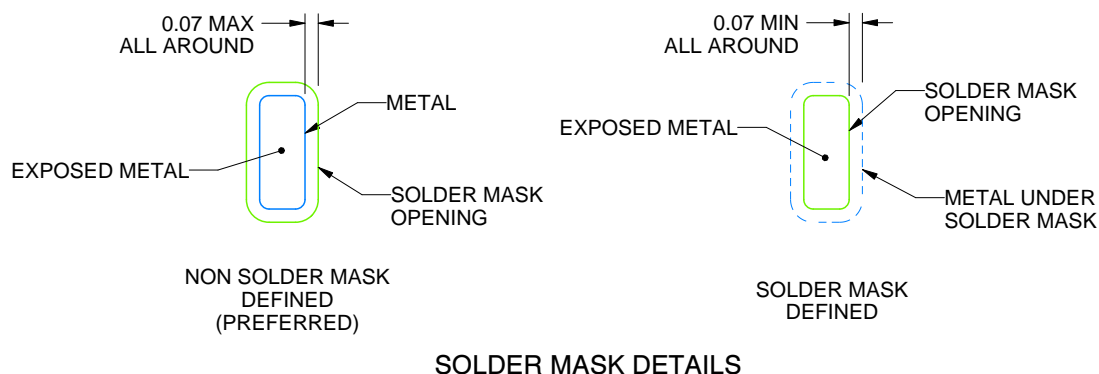
RGZ0048B

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:12X



SOLDER MASK DETAILS

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NOTES: (continued)

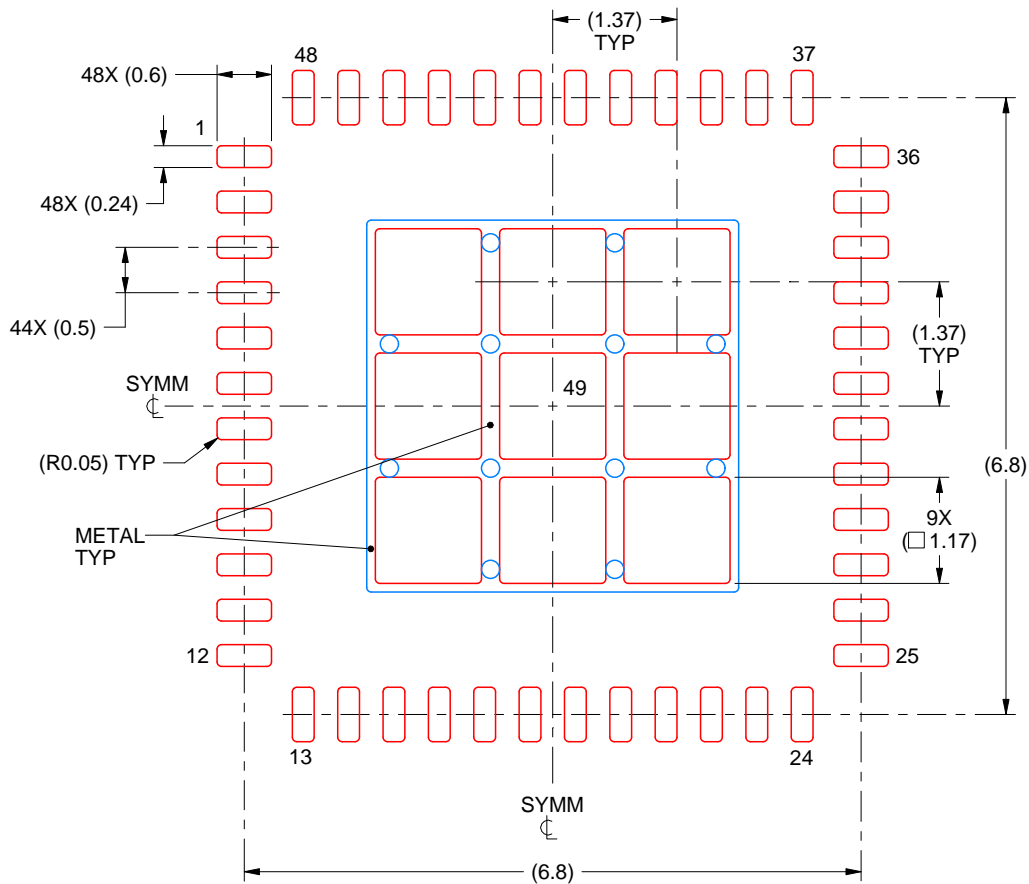
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RGZ0048B

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 49
73% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:12X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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